

ABSTRACTPROCESS FOR THE FORMATION OF A SILICON LAYER ON A
SUPPORT FOR OPTICAL PURPOSES, AND USE OF THE PROCESS TO
MAKE OPTICAL COMPONENTS

The invention relates to a process for the formation of a silicon layer (22a) with a determined thickness on a support (10), for optical purposes. The process comprises the following steps:

- 5 a) molecular bonding of a silicon block (20a) on the support, the silicon block having a surface layer (22a) delimited by a cleavage area,
- b) cleavage of the silicon block along the cleavage area to detach the surface layer from it,
- 10 c) adjustment of the thickness of the said surface layer.

Applications to the manufacture of optical components.

15 Figure 3.